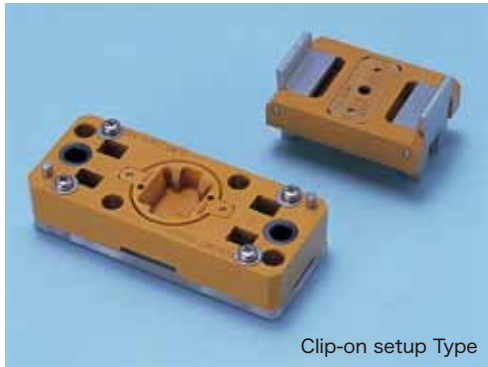
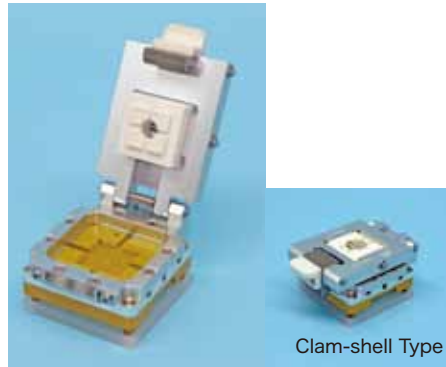


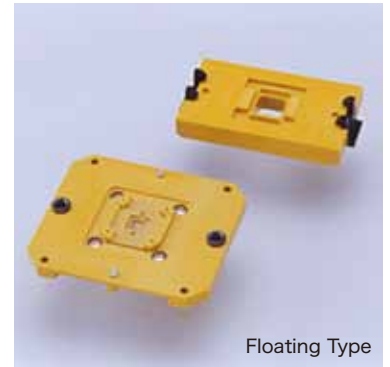
IC Test Sockets (for BGA/LGA/QFN/QFP/SSOP)



Clip-on setup Type



Clam-shell Type



Floating Type

BGA / LGA / QFN Test Socket

QFP / SSOP Test Socket

Applications

- BGA / LGA / QFN / QFP / SSOP package function test
- BGA / LGA / QFN / QFP / SSOP package burn-in test

Features

- Adopting high performance, high durability and high reliability contact probe.
- Contact probes can be removed one by one, enabling the user to perform a maintenance swiftly.
- Wide range of probe variations, (from 0.3mm to 1.27mm pitch)
- Incorporating standard contact probes make the custom socket design available.
- Available to test wafer level CSP test and prototype IC.
- Available to test PoP package (both Top & Bottom contact / Top contactor with Memory).

Specification

Socket Design	Open-top, Clam-shell, Clip-on setup
Pitch	0.3mm ~ 1.27mm
Operating Temperature	-55°C ~ +125°C (+150°C)*
Fabrication	Molded or Milling
Material	Super engineering plastic

* Customized for 150°C case